

September 2014

MPSA06 / MMBTA06 / PZTA06 NPN General-Purpose Amplifier

Features

- This device is designed for general-purpose amplifier applications at collector currents to 300 mA.
- Sourced from process 12.



Ordering Information

Part Number	Top Mark	Top Mark Package			
MPSA06	MPSA06	TO-92 3L	Bulk		
MMBTA06	1G	SOT-23 3L	Tape and Reel		
PZTA06	A06	SOT-223 4L	Tape and Reel		

Absolute Maximum Ratings(1), (2)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}\text{C}$ unless otherwise noted.

Symbol	Parameter	Value	Unit
V _{CEO}	Collector-Emitter Voltage	80	V
V _{CBO}	Collector-Base Voltage	80	V
V _{EBO}	Emitter-Base Voltage	4.0	V
I _C	Collector Current - Continuous	500	mA
T _{J,} T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

Notes:

- 1. These ratings are based on a maximum junction temperature of 150°C.
- 2. These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

Thermal Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter		Unit			
Syllibol	Farameter	MPSA06	MMBTA06 ⁽³⁾	PZTA06 ⁽⁴⁾	Oilit	
В	Total Device Dissipation	625	350	1000	mW	
P _D	Derate Above 25°C	5.0	2.8	8.0	mW/°C	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	83.3			°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	200	357	125	°C/W	

Notes:

- 3. Device is mounted on FR-4 PCB 1.6 inch x 1.6 inch x 0.06 inch.
- 4. Device is mounted on FR-4 PCB 36 mm x 18 mm x 1.5 mm, mounting pad for the collector lead minimum 6 cm².

Electrical Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Max.	Unit
Off Charact	teristics			•	
V _{(BR)CEO}	Collector-Emitter Breakdown Voltage ⁽⁵⁾	$I_C = 1.0 \text{ mA}, I_B = 0$	80		V
V _{(BR)EBO}	Emitter-Base Breakdown Voltage	$I_E = 100 \mu A, I_C = 0$	4.0		V
I _{CEO}	Collector Cut-Off Current	$V_{CE} = 60 \text{ V}, I_{B} = 0$		0.1	μΑ
I _{CBO}	Collector Cut-Off Current	$V_{CB} = 80 \text{ V}, I_{E} = 0$		0.1	μΑ
On Charact	eristics		•		•
h	DC Current Gain	$I_C = 10 \text{ mA}, V_{CE} = 1.0 \text{ V}$	100		
h _{FE}	De current Gain	I _C = 100 mA, V _{CE} = 1.0 V	100		
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C = 100 mA, I _B = 10 mA		0.25	V
V _{BE(on)}	Base-Emitter On Voltage	$I_C = 100 \text{ mA}, V_{CE} = 1.0 \text{ V}$		1.2	V
Small Signa	al Characteristics	•		•	
f _T	Current Gain - Bandwidth Product	$I_C = 10 \text{ mA}, V_{CE} = 2.0 \text{ V},$ f = 100 MHz	100		MHz

Notes:

5. Pulse test: pulse width \leq 300 μ s, duty cycle \leq 2%.

Typical Performance Characteristics

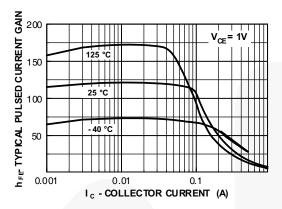


Figure 1. Typical Pulsed Current Gain vs. Collector Current

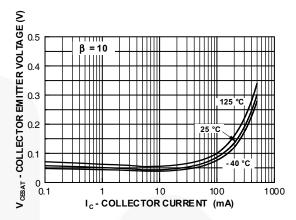


Figure 2. Collector-Emitter Saturation Voltage vs. Collector Current

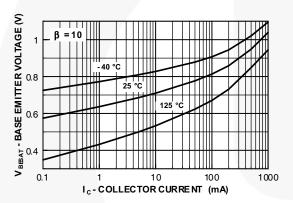


Figure 3. Base-Emitter Saturation Voltage vs. Collector Current

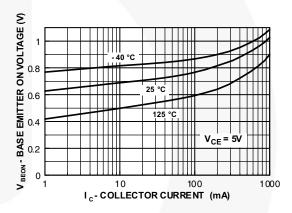


Figure 4. Base-Emitter On Voltage vs. Collector Current

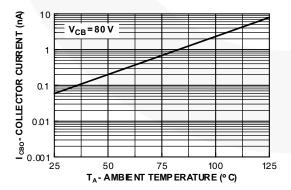


Figure 5. Collector Cut-Off Current vs.
Ambient Temperature

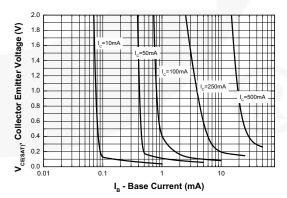


Figure 6. Collector Saturation Region

Typical Performance Characteristics (Continued)

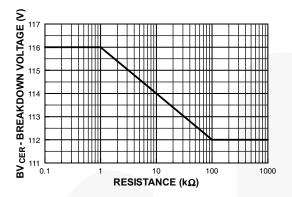


Figure 7. Collector-Emitter Breakdown Voltage with Resistance Between Emitter-Base

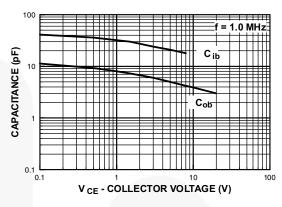


Figure 8. Input and Output Capacitance vs. Reverse Current

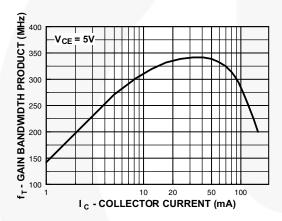


Figure 9. Gain Bandwidth Product vs. Collector Current

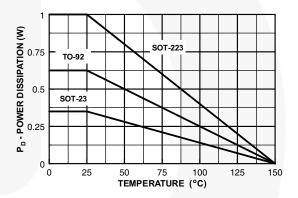
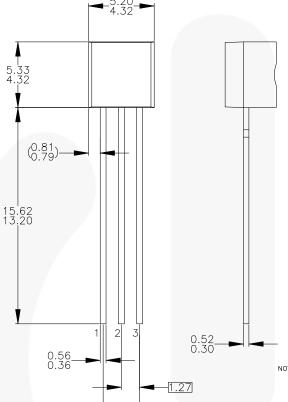


Figure 10. Power Dissipation vs.
Ambient Temperature

Physical Dimensions



2.54

2

4.19 3.05

NOTES: UNLESS OTHERWISE SPECIFIED

- DRAWING WITH REFERENCE TO JEDEC TO-92 RECOMMENDATIONS.
 ALL DIMENSIONS ARE IN MILLIMETERS.
 DRAWING CONFORMS TO ASME Y14.5M-1994.
 TO-92 (92,94,96,97,98) PIN CONFIGURATION:

Z		92		94		96			97			98			
Φ.	Р	F	М	Р	F	М	В	F	М	Р	F	М	Р	F	М
1	Ε	S	S	Ε	S	S	В	D	G	С	G	D	С	G	D
2	В	D	G	С	G	D	Ε	S	S	В	D	G	Ε	S	S
3	С	G	D	В	D	G	С	G	D	Ε	S	S	В	D	G

LEGEND:

- P BIPOLAR F JFET M DMOS – EMITTER– BASE– COLLECTOR D - DRAIN S - SOURCE G - GATE
 - E) FOR PACKAGE 92, 94, 96, 97 AND 98:
 PIN CONFIGURATION DRAIN "D" AND SOURCE "S"
 ARE INTERCHANGEAGLE AT JETE "F" OPTION.
 F) DRAWING FILENAME: MKT-ZAO3DREV3.

Figure 11. 3-LEAD, TO-92, MOLDED, STD STRAIGHT LEAD (NO EOL CODE)

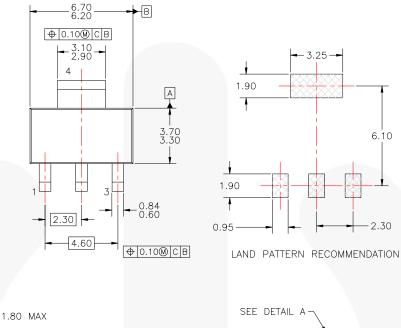
2.66 2.13

Physical Dimensions (Continued) 0.95 2.92±0.20 3 1.40 1.30+0.20 2.20 2 0.60 0.37 (0.29) -0.95 ⊕ | 0.20 M | A | B 1.00 1.90 1.90 LAND PATTERN RECOMMENDATION SEE DETAIL A 1.20 MAX (0.93)0.10 0.00 ○ 0.10 M C С 2.40±0.30 NOTES: UNLESS OTHERWISE SPECIFIED **GAGE PLANE** A) REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H. B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.23 0.08 C) DIMENSIONS ARE INCLUSIVE OF BURRS, 0.25 MOLD FLASH AND TIE BAR EXTRUSIONS. D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 1994. 0.20 MIN SEATING E) DRAWING FILE NAME: MA03DREV10 **PLANE** (0.55)**DETAIL A** SCALE: 2X

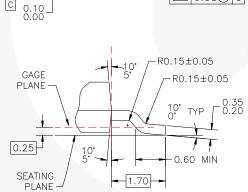
Figure 12. 3-LEAD, SOT23, JEDEC TO-236, LOW PROFILE

Physical Dimensions (Continued)

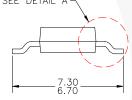
C



△ 0.08M C



DETAIL A



NOTES: UNLESS OTHERWISE SPECIFIED

- DRAWING BASED ON JEDEC
 REGISTRATION TO-261, VARIATION AA.
 DIMENSIONS ARE INCLUSIVE OF BURRS,
 MOLD FLASH AND TIE BAR EXTRUSIONS.
 ALL DIMENSIONS ARE IN MILLIMETERS.
 DRAWING CONFORMS TO ASME
 Y14.5M-1994.
 LANDPATTERN NAME:
 S0T230P700X180-4BN
 DRAWING FILENAME: MKT-MA04AREV2

- E)

Figure 13. MOLDED PACKAGING, SOT-223, 4-LEAD





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

AccuPower™ F-PFS™ Awinda® FRFET® AX-CAP®* Global F

 $\begin{array}{ccc} \mathsf{CorePOWER^{\intercal M}} & \mathsf{G\textit{max}^{\intercal M}} \\ \mathsf{C\textit{ROSSVOLT}^{\intercal M}} & \mathsf{GTO}^{\intercal M} \\ \mathsf{CTL}^{\intercal M} & \mathsf{IntelliMAX}^{\intercal M} \\ \end{array}$

Current Transfer Logic™ ISOPLANAR™
DEUXPEED® Making Small St

DEUXPEED® Making Small Speakers Sound Louder
Dual Cool™ and Better™
ECOSDABK® Mass Dual™

EcoSPARK® MegaBuck™
EfficientMax™ MICROCOUPLER™
ESBC™ MicroFET™

Fairchild® MicroPak™
Fairchild Semiconductor® FACT Quiet Series™ MotionMax™
MotionGrid®
MotionGrid®

FACT® MotionGrid
FAST® MTI®
FastvCore™ MTx®
FETBench™ mWN®
FPS™ OptoHiT™

PowerTrench[®] PowerXS™

Programmable Active Droop™

QFET®
QS™
Quiet Series™
RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-6
SuperSOT™-8
SupreMOS®
SyncFET™

Sync-Lock™

TinyBoost®
TinyBuck®
TinyCalc™
TinyLogic®
TiNYOPTO™
TinyPower™
TinyPWM™
TinyWire™
TranSiC™
TriFault Detect™
TRUECURRENT®*
µSerDes™

SerDes'
UHC®
UItra FRFET™
UniFET™
VCX™
VisualMax™
VoltagePlus™
XS™
Xsens™

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT http://www.fairchildsemi.com, FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Definition of Terms						
Datasheet Identification		Definition				
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.				
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.				
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.				
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.				

Rev. 171

^{*} Trademarks of System General Corporation, used under license by Fairchild Semiconductor.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Fairchild Semiconductor: PZTA06